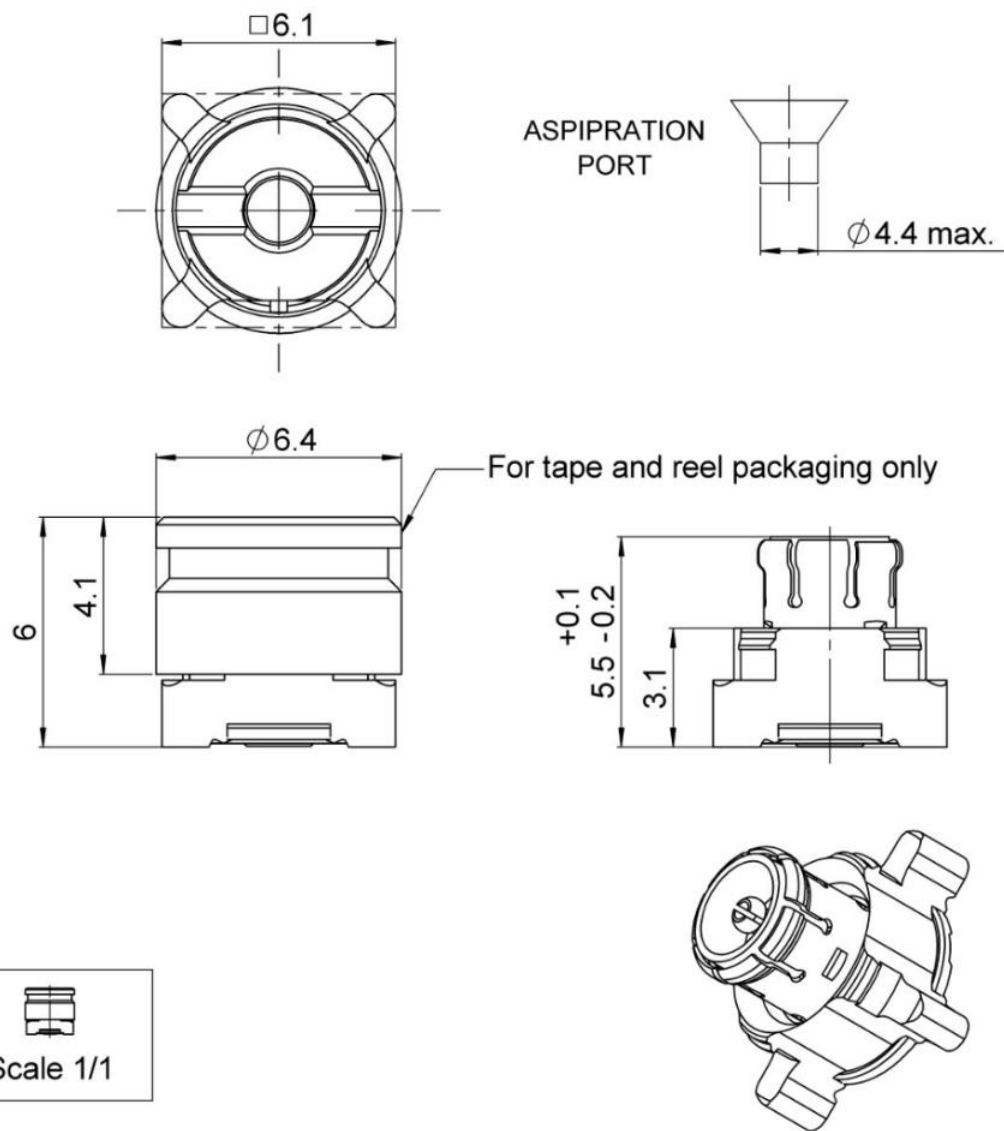
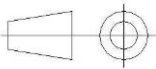


PAGE 1/5	ISSUE 17-07-20A	SERIES MMBX	PART NUMBER R223434926
----------	-----------------	-------------	------------------------



All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	BERYLLIUM COPPER; BRASS	BBR OVER SILVER
Center contact	BERYLLIUM COPPER; BRASS	Silver
Outer contact		
Insulator	LCP	
Gasket	PTFE	
Others parts		
-	-	-
-	-	-

PAGE 2/5	ISSUE 17-07-20A	SERIES MMBX	PART NUMBER R223434926
----------	-----------------	-------------	------------------------

PACKAGING

Standard	Unit	Other
750	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-12.4	GHz
VSWR	*1.065 +	0	x F(GHz) Maxi
Insertion loss		0.12	√F(GHz) dB Maxi
RF leakage	- (**100	- F(GHz)) dB Maxi
Voltage rating		330	Veff Maxi
Dielectric withstanding voltage		1000	Veff mini
Insulation resistance		1000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End	NA	N mini	
Axial force – Opposite end	NA	N mini	
Torque	NA	N.cm mini	

Recommended torque			
Mating	NA	N.cm	
Panel nut	NA	N.cm	

Mating life	100	Cycles mini	
Nominal Weight	0,58	g	
(Add +15% for max weight)			

ENVIRONMENTAL

Operating temperature	-55/+155	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction: NA

Others:

* Up to 2GHz ; 1.106max @ 2-6 GHz

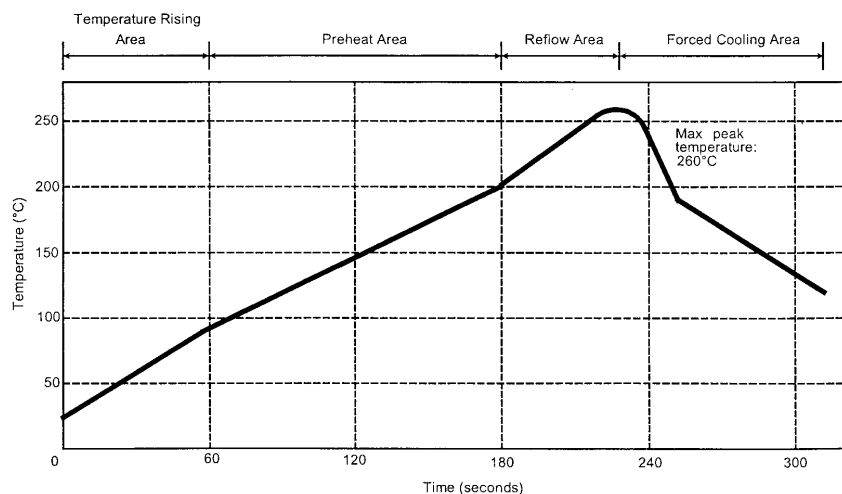
**Interface only, up to 2.5 GHz

PIM3<= -140dBc, 2x30dBm @700,900,1800,2600MHz

SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

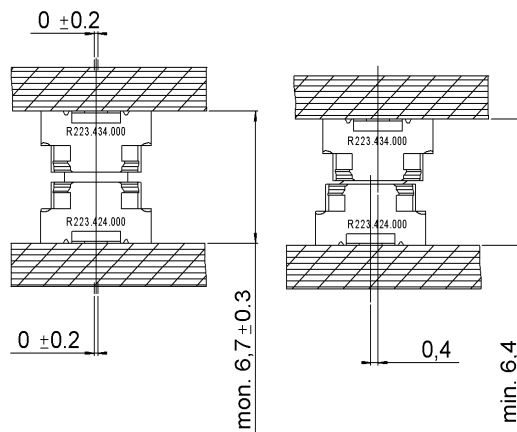
PAGE 5/5

ISSUE 17-07-20A

SERIES MMBX

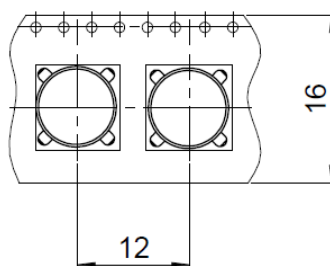
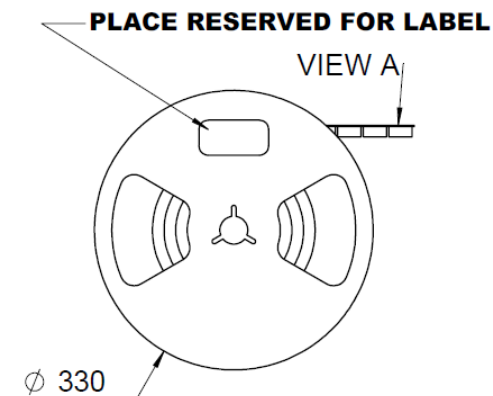
PART NUMBER R223434926

SET INFORMATIONS



Only for set illustration.

PACKAGE



View A